

Amolt -OK- to enter

-gmo 11/3/06

AMENDMENTS TO CLAIMS

- Please amend pending claim 16 as indicated below. A complete listing of all claims and their status in the application are as follows:

1. (previously presented) A method for fabricating a semiconductor package, comprising:

providing a substrate in a strip format;
attaching semiconductor devices in a strip format to the substrate;
applying an underfill between the semiconductor devices and the substrate;
applying a thin thermal interface material to the semiconductor devices;
attaching a flat panel heat spreader to the thermal interface material on each semiconductor device;
encapsulating substantially all of the volume between the heat spreader and the substrate, except that occupied by the semiconductor devices and other electronic devices assembled on the substrate, with open encapsulation, leaving the surface of the flat panel heat spreader opposite the substrate externally exposed; and
singulating individual semiconductor packages from the strip format.

2. (original) The method of claim 1 wherein the heat spreader is a pre-cut flat panel configuration.

3. (original) The method of claim 1 wherein the heat spreader is a continuous flat panel heat spreader attached over substantially the entire strip format.

4. (original) The method of claim 3 further comprising cutting the continuous flat panel heat spreader into individual heat spreader panels following attaching the flat panel heat spreader.

5. (original) The method of claim 3 further comprising dispensing an encapsulant for encapsulating the semiconductor devices and for attaching the flat panel heat spreader prior to attaching the flat panel heat spreader.

6. (previously presented) A method for fabricating a semiconductor package, comprising:

providing a substrate in a continuous strip format;